CD14538B Types

CMOS Dual Precision Monostable Multivibrator

High-Voltage Types (20-Volt Rating)

Features:
- *Retriggerable/resettable capability*
- *Trigger and reset propagation delays independent of R_x, C_x*
- *Triggering from leading or trailing edge*
- *Q and $\overline{Q}$ buffered outputs available*
- *Separate resets*
- *Replaces CD4538B Type*

CD14538B FUNCTIONAL DIAGRAM

■ CD14538B dual precision monostable multi-vibrator provides stable retriggerable/resettable one-shot operation for any fixed-voltage timing application.

An external resistor (R_x) and an external capacitor (C_x) control the timing and accuracy for the circuit. Adjustment of R_x and C_x provides a wide range of output pulse widths from the Q and $\overline{Q}$ terminals. The time delay from trigger input to output transition (trigger propagation delay) and the time delay from reset input to output transition (reset propagation delay) are independent of R_x and C_x. Precision control of output pulse widths is achieved through linear CMOS techniques.

Leading-edge-triggering (+TR) and trailing-edge-triggering (–TR) inputs are provided for triggering from either edge of an input pulse. An unused +TR input should be tied to V_{ss}. An unused –TR input should be tied to V_{DD}. A RESET (on low level) is provided for immediate termination of the output pulse or to prevent output pulses when power is turned on. An unused RESET input should be tied to V_{DD}. However, if an entire section of the CD14538B is not used, its inputs must be tied to either V_{DD} or V_{ss}. See Table I.

In normal operation the circuit retriggers (extends the output pulse one period) on the application of each new trigger pulse. For operation in the non-retriggerable mode, $\overline{Q}$ is connected to –TR when leading-edge triggering (+TR) is used or Q is connected to +TR when trailing-edge triggering (–TR) is used. The time period (T) for this multivibrator can be calculated by: $T = R_xC_x$.

The minimum value of external resistance, R_x, is 4 KΩ. The minimum and maximum values of external capacitance, C_x, are 0 pF and 100 μF, respectively.

The CD14538B is interchangeable with type MC14538 and is similar to and pin-compatible with the CD4098B* and CD4538B. It can replace the CD4538B which type is not recommended for new designs.

The CD14538B types are supplied in 16-lead hermetic dual-in-line ceramic packages (F3A suffix), 16-lead dual-in-line plastic packages (E suffix), 16-lead small-outline packages (M, M96, MT, and NSR suffixes), and 16-lead thin shrink small-outline packages (PW and PWR suffixes).

*T = 0.5 R_xC_x for $C_x \geq$ 1000 pF   #T = R_xC_x; $C_x$min = 5000 pF
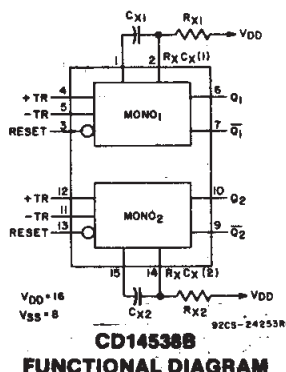
- *Wide range of output-pulse widths*
- *Schmitt-trigger input allows unlimited rise and fall times on +TR and –TR inputs*
- *100% tested for maximum quiescent current at 20 V*
- *Maximum input current of 1 μA at 18 V over full package-temperature range; 100 nA at 18 V and 25°C*
- *Noise margin (full package-temperature range):*
    - *1 V at V_{DD} = 5 V*
    - *2 V at V_{DD} = 10 V*
    - *2.5 V at V_{DD} = 15 V*
- *5-V, 10-V, and 15-V parametric ratings*
- *Standardized, symmetrical output characteristics*
- *Meets all requirements of JEDEC Tentative Standard No. 13B, "Standard Specifications for Description of 'B' Series CMOS Devices."*

Applications:
- *Pulse delay and timing*
- *Pulse shaping*

TOP VIEW
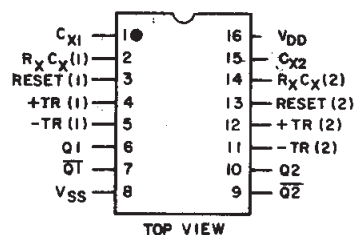
TERMINALS 1, 8, 15 ARE ELECTRICALLY CONNECTED INTERNALLY

Terminal Assignment

CD14538B Types

MAXIMUM RATINGS, *Absolute-Maximum Values:*

DC SUPPLY-VOLTAGE RANGE, (V_{DD})
Voltages referenced to V_{SS} Terminal) .... –0.5V to +20V
INPUT VOLTAGE RANGE, ALL INPUTS .... –0.5V to V_{DD} +0.5V
DC INPUT CURRENT, ANY ONE INPUT .... ±10mA
POWER DISSIPATION PER PACKAGE (P_D):
For T_A = –55°C to +100°C 500mW
For T_A = +100°C to +125°C .... Derate Linearly at 12mW/°C to 200mW
DEVICE DISSIPATION PER OUTPUT TRANSISTOR
FOR T_A = FULL PACKAGE-TEMPERATURE RANGE (All Package Types) 100mW
OPERATING-TEMPERATURE RANGE (T_A) .... –55°C to +125°C
STORAGE TEMPERATURE RANGE (T_{stg}) .... –65°C to +150°C
LEAD TEMPERATURE (DURING SOLDERING):
At distance 1/16 ± 1/32 inch (1.59 ± 0.79mm) from case for 10s max .... +265°C

RECOMMENDED OPERATING CONDITIONS
**For maximum reliability, nominal operating conditions should be selected
so that operating is always within the following ranges:**

CHARACTERISTIC	V_{DD} (V)	LIMITS Min.	LIMITS Max.	UNITS
Supply-Voltage Range (For T_A=Full Package-Temperature Range)	—	3	18	V
Input Pulse Width +TR, –TR, or RESET t_{WH}, t_{WL}	5	140	—	
	10	80	—	ns
	15	60	—	

TABLE I
CD4538B FUNCTIONAL TERMINAL CONNECTIONS

FUNCTIION	V_{DD} TO TERM. NO. MONO₁	V_{DD} TO TERM. NO. MONO₂	V_{SS} TO TERM. NO. MONO₁	V_{SS} TO TERM. NO. MONO₂	INPUT PULSE TO TERM. NO. MONO₁	INPUT PULSE TO TERM. NO. MONO₂	OTHER CONNECTIONS MONO₁	OTHER CONNECTIONS MONO₂
Leading-Edge Trigger/ Retriggerable	3, 5	11, 13			4	12		
Leading-Edge Trigger/ Non-Retriggerable	3	13			4	12	5-7	11-9
Trailing-Edge Trigger/ Retriggerable	3	13	4	12	5	11		
Trailing-Edge Trigger/ Non-Retriggerable	3	13			5	11	4-6	12-10

NOTES:
1. A RETRIGGERABLE ONE-SHOT MULTIVIBRATOR HAS AN OUTPUT PULSE WIDTH WHICH IS EXTENDED ONE FULL TIME PERIOD (T) AFTER APPLICATION OF THE LAST TRIGGER PULSE.

2. A NON—RETRIGGERABLE ONE-SHOT MULTIVIBRATOR HAS A TIME PERIOD (T) REFERENCED FROM THE APPLICATION OF THE FIRST TRIGGER PULSE.

INPUT PULSE TRAIN

RETRIGGERABLE MODE PULSE WIDTH (+TR MODE)

NON-RETRIGGERABLE MODE PULSE WIDTH (+TR MODE)

STATIC ELECTRICAL CHARACTERISTICS

CHARACTERISTIC	CONDITIONS			LIMITS AT INDICATED TEMPERATURES (°C)							UNITS
	V_O (V)	V_{IN} (V)	V_{DD} (V)	−55	−40	+85	+125	Min.	+25 Typ.	Max.	
Quiescent Device Current, I_{DD} Max.	—	0,5	5	5	5	150	150	—	0.04	5	μA
	—	0,10	10	10	10	300	300	—	0.04	10	
	—	0,15	15	20	20	600	600	—	0.04	20	
	—	0,20	20	100	100	3000	3000	—	0.08	100	
Output Low (Sink) Current, I_{OL} Min.	0.4	0,5	5	0.64	0.61	0.42	0.36	0.51	1	—	mA
	0.5	0,10	10	1.6	1.5	1.1	0.9	1.3	2.6	—	
	1.5	0,15	15	4.2	4	2.8	2.4	3.4	6.8	—	
Output High (Source) Current, I_{OH} Min.	4.6	0,5	5	−0.64	−0.61	−0.42	−0.36	−0.51	−1	—	
	2.5	0,5	5	−2	−1.8	−1.3	−1.15	−1.6	−3.2	—	
	9.5	0,10	10	−1.6	−1.5	−1.1	−0.9	−1.3	−2.6	—	
	13.5	0,15	15	−4.2	−4	−2.8	−2.4	−3.4	−6.8	—	
Output Voltage: Low-Level, V_{OL} Max.	—	0,5	5	0.05				—	0	0.05	V
	—	0,10	10	0.05				—	0	0.05	
	—	0,15	15	0.05				—	0	0.05	
Output Voltage: High-Level, V_{OH} Min.	—	0,5	5	4.95				4.95	5	—	
	—	0,10	10	9.95				9.95	10	—	
	—	0,15	15	14.95				14.95	15	—	
Input Low Voltage, V_{IL} Max.	0.5,4.5	—	5	1.5				—	—	1.5	V
	1,9	—	10	3				—	—	3	
	1.5,13.5	—	15	4				—	—	4	
Input High Voltage, V_{IH} Min.	0.5,4.5	—	5	3.5				3.5	—	—	
	1,9	—	10	7				7	—	—	
	1.5,13.5	—	15	11				11	—	—	
Input Current, I_{IN} Max.	—	0,18	18	±0.1	±0.1	±1	±1	—	±10⁻⁵	±0.1	μA
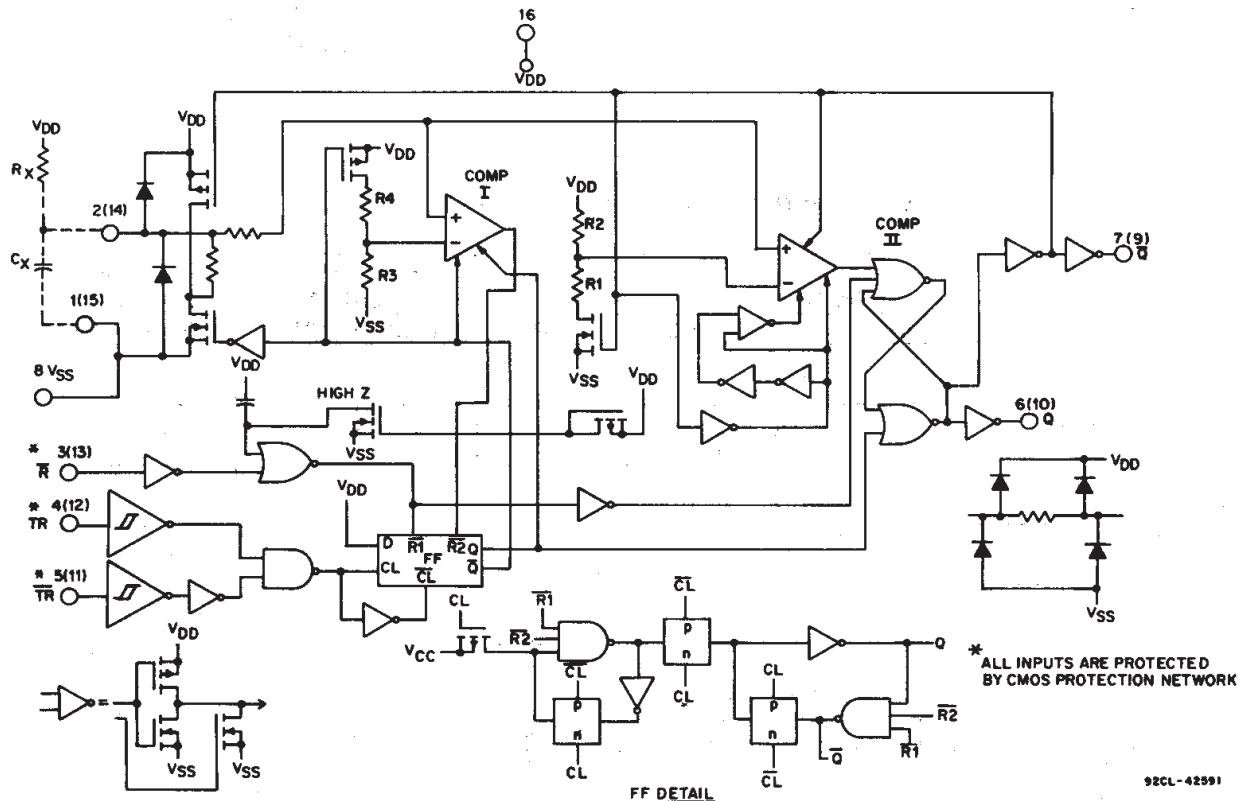
Fig. 1 - Logic diagram (½ of device shown).

DYNAMIC ELECTRICAL CHARACTERISTICS, At T_A=25° C; Input t_r,t_f=20 ns, C_L=50 pF

CHARACTERISTIC		TEST CONDITIONS V_{DD} (V)	LIMITS			UNITS
			Min.	Typ.	Max.	
Transition Time	t_{TLH}, t_{THL}	5	—	100	200	
		10	—	50	100	
		15	—	40	80	
Propagation Delay Time:	t_{PLH}, t_{PHL}	5	—	300	600	
+TR or –TR to Q or $\overline{Q}$		10	—	150	300	
		15	—	100	220	ns
Reset to Q or $\overline{Q}$		5	—	250	500	
		10	—	125	250	
		15	—	95	190	
Minimum Input Pulse Width:	t_{WH}, t_{WL}	5	—	80	140	
+TR, –TR or Reset		10	—	40	80	
		15	—	30	60	
Output Pulse Width - Q or $\overline{Q}$:	T	5	198	210	230	
C_X = 0.002 μF, R_X = 100 KΩ		10	200	212	232	μs
		15	202	214	234	
C_X=0.1 μF, R_X=100 KΩ		5	9.4	9.97	10.5	
		10	9.4	9.95	10.6	ms
		15	9.5	10	10.6	
C_X=10 μF, R_X=100 KΩ		5	0.95	1	1.06	
		10	0.95	1	1.06	s
		15	0.96	1.01	1.07	
Pulse Width Match between	$\frac{100\ (T_1-T_2)}{T_1}$	5	—	±1	—	
circuits in same package:		10	—	±1	—	%
C_X=0.1 μF, R_X=100 KΩ		15	—	±1	—	
Minimum Retrigger Time	t_{rr}	5	0	—	—	
		10	0	—	—	ns
		15	0	—	—	
Input Capacitance	C_{IN}	Any Input	—	5	7.5	pF

*Note: Minimum R_X value=4 KΩ, minimum C_X value=5000 pF.
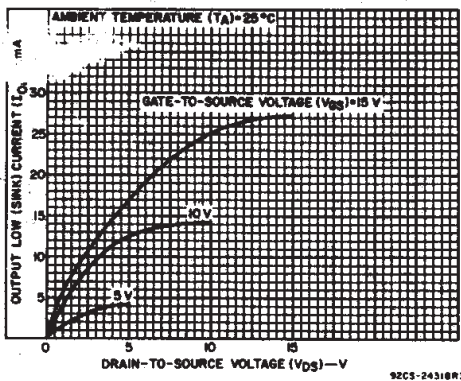
Fig. 2 - Typical output low (sink) current characteristics.
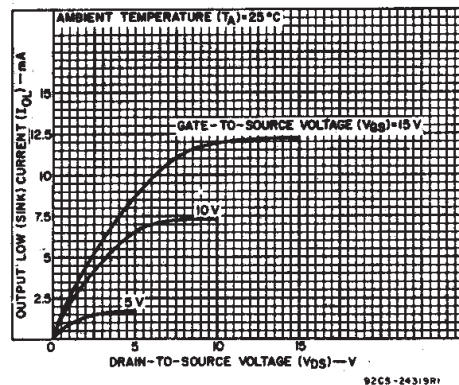
Fig. 3 - Minimum output low (sink) current characteristics.
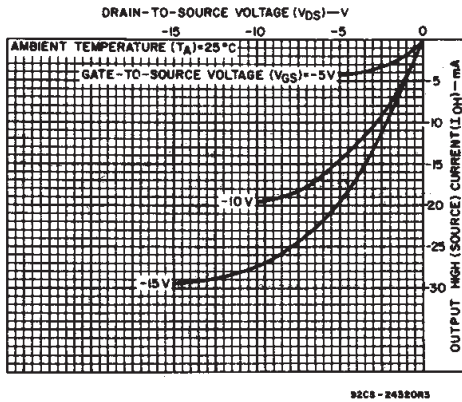
Fig. 4 - Typical output high (source) current characteristics.
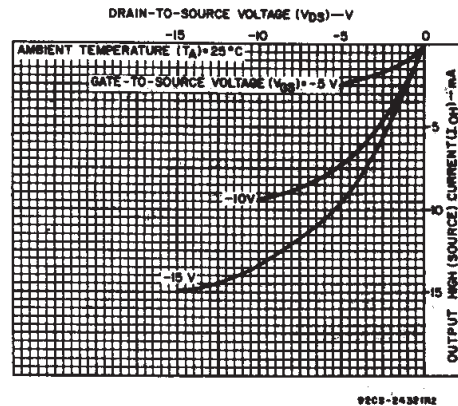
Fig. 5 - Minimum output high (source) current characteristics.

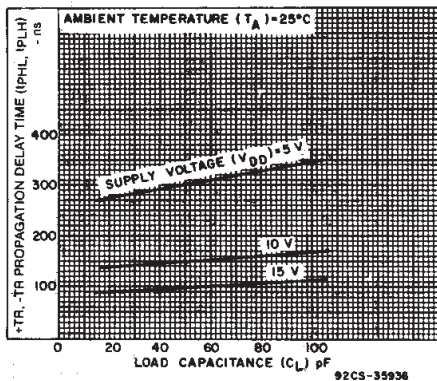Fig. 6 - Typical propagation delay time as a function of load capacitance (+TR or −TR to Q or $\overline{Q}$).
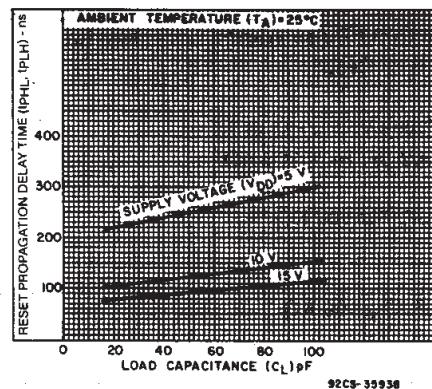

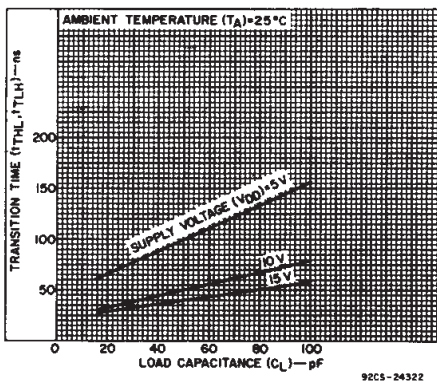Fig. 7 - Typical propagation delay time as a function of load capacitance (RESET to Q or $\overline{Q}$).

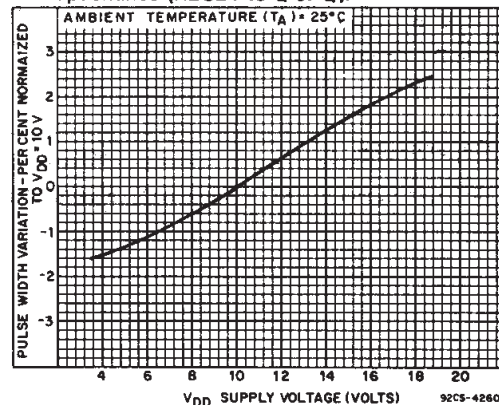Fig. 8 - Typical transition time as a function of load capacitance.
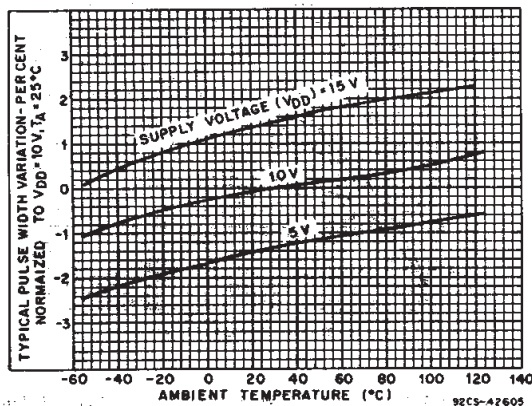

Fig. 9 - Typical pulse-width variation as a function of supply voltage.

Fig. 10 - Typical pulse-width variation as a function of temperature (R_x=100 KΩ, C_x=0.1 μF).
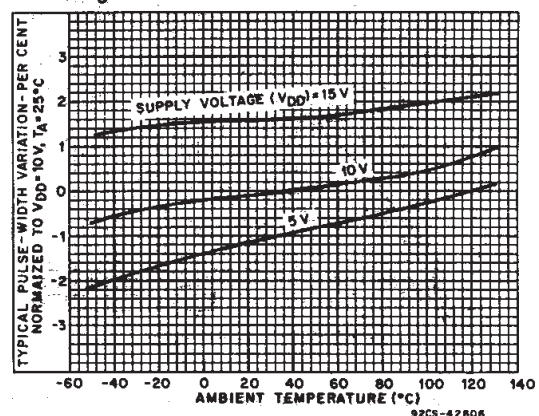
Fig. 11 - Typical pulse-width variation as a function of temperature (R_x=100 KΩ, C_x=2000 pF).

3-368
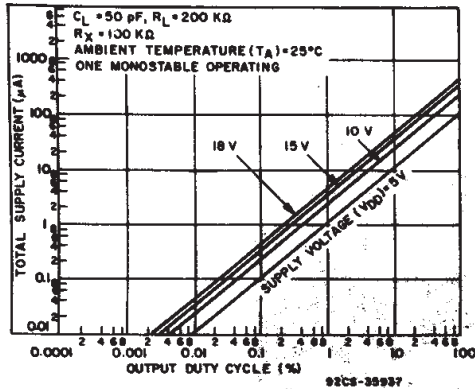
Fig. 12 - Typical total supply current as a function of output duty cycle.

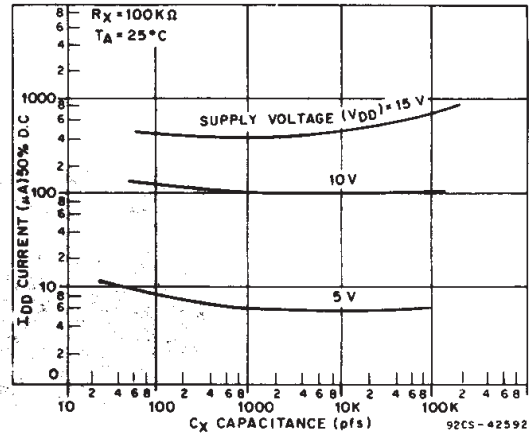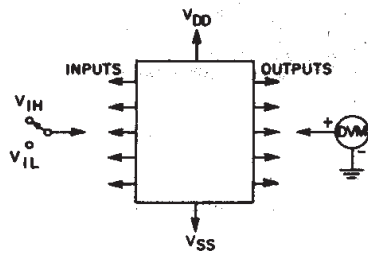Fig. 13 - Typical total supply current as a function of load capacitance.

NOTE:
1. Test any combination of inputs.
2. When measuring V_{IH} or V_{IL} for Schmitt trigger inputs (+TR, -TR), the input must first be brought to V_{DD} or V_{SS}, respectively, then reduced to the specified limit.
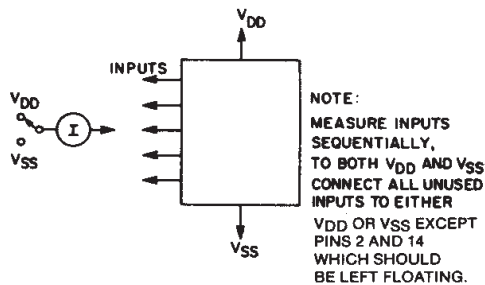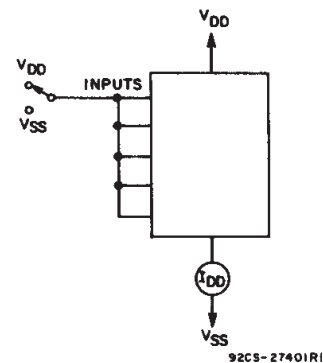
Fig. 14 - Input voltage test circuit.

NOTE:
MEASURE INPUTS SEQUENTIALLY, TO BOTH V_{DD} AND V_{SS}. CONNECT ALL UNUSED INPUTS TO EITHER V_{DD} OR V_{SS} EXCEPT PINS 2 AND 14 WHICH SHOULD BE LEFT FLOATING.

Fig. 15 - Input leakage-current test circuit.

Fig. 16 - Quiescent device current test circuit.

Power-Down Mode

During a rapid power-down condition, as would occur with a power-supply short circuit or with a poorly filtered power supply, the energy stored in C_X could discharge into Pin 2 or 14. To avoid possible device damage in this mode, when C_X is ≥ 0.5 microfarad, a protection diode with a 1-ampere or higher rating (1N5395 or equivalent) and a separate ground return for C_X should be provided as shown in Fig. 17.
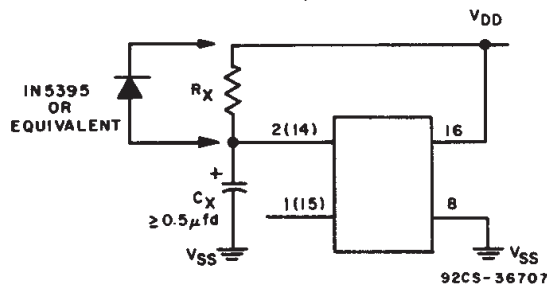
An alternate protection method is shown in Fig. 18, where a 51-ohm current-limiting resistor is inserted in series with C_X. Note that a small pulse width decrease will occur however, and R_X must be appropriately increased to obtain the originally desired pulse width.
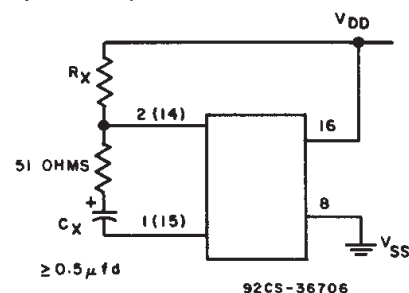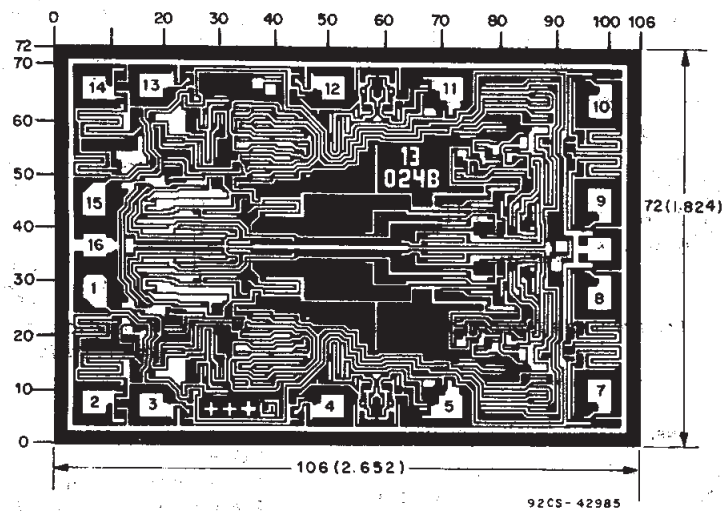

Fig. 17 - Rapid power-down protection circuit.

Fig. 18 - Alternate rapid power-down protection circuit.

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Dimensions in parentheses are in millimeters and are derived from the basic inch dimensions as indicated. Grid graduations are in mils (10^{-3} inch).

Dimensions and pad layout for CD14538BH.

PACKAGE OPTION ADDENDUM

![Texas Instruments logo]

PACKAGING INFORMATION

Orderable Device	Status [1]	Package Type	Package Drawing	Pins	Package Qty	Eco Plan [2]	Lead/Ball Finish	MSL Peak Temp [3]
5962-9055701EA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type
CD14538BE	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
CD14538BEE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
CD14538BF	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type
CD14538BF3A	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type
CD14538BM	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD14538BM96	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD14538BM96E4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD14538BM96G4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD14538BME4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD14538BMG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD14538BMT	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD14538BMTE4	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD14538BMTG4	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD14538BNSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD14538BNSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD14538BNSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD14538BPW	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD14538BPWE4	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD14538BPWG4	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD14538BPWR	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD14538BPWRE4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD14538BPWRG4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

[1] The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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TAPE AND REEL INFORMATION

REEL DIMENSIONS

Reel Diameter

Reel Width (W1)

TAPE DIMENSIONS

Cavity

A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

Sprocket Holes

User Direction of Feed

Pocket Quadrants

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CD14538BM96	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
CD14538BNSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
CD14538BPWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CD14538BM96	SOIC	D	16	2500	333.2	345.9	28.6
CD14538BNSR	SO	NS	16	2000	346.0	346.0	33.0
CD14538BPWR	TSSOP	PW	16	2000	346.0	346.0	29.0

J (R-GDIP-T**)   CERAMIC DUAL IN-LINE PACKAGE
14 LEADS SHOWN

DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)

B

14   8

1   7

0.065 (1,65)
0.045 (1,14)

C

0.005 (0,13) MIN

0.060 (1,52)
0.015 (0,38)

0.200 (5,08) MAX

Seating Plane

0.130 (3,30) MIN

A

0.026 (0,66)
0.014 (0,36)

0.100 (2,54)

0°-15°

0.014 (0,36)
0.008 (0,20)

4040083/F 03/03

NOTES: A. All linear dimensions are in inches (millimeters).
         B. This drawing is subject to change without notice.
         C. This package is hermetically sealed with a ceramic lid using glass frit.
         D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
         E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

N (R−PDIP−T**)   PLASTIC DUAL−IN−LINE PACKAGE

16 PINS SHOWN

DIM \ PINS **	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS−001 VARIATION	AA	BB	AC	AD

0.260 (6,60) / 0.240 (6,10)

0.070 (1,78) / 0.045 (1,14) ⚠D

0.045 (1,14) / 0.030 (0,76) ⚠D

0.020 (0,51) MIN

0.200 (5,08) MAX

Seating Plane

0.125 (3,18) MIN

0.100 (2,54)

0.021 (0,53) / 0.015 (0,38)

⊕ 0.010 (0,25) Ⓜ

14/18 Pin Only
20 Pin vendor option ⚠D

0.325 (8,26) / 0.300 (7,62)

0.015 (0,38)

Gauge Plane

0.010 (0,25) NOM

0.430 (10,92) MAX

4040049/E 12/2002

NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
⚠C Falls within JEDEC MS−001, except 18 and 20 pin minimum body length (Dim A).
⚠D The 20 pin end lead shoulder width is a vendor option, either half or full width.

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D (R−PDSO−G16)   PLASTIC SMALL OUTLINE

$\dfrac{0.394\ (10,00)}{0.386\ (9,80)}$ ⟨C⟩

16   9

$\dfrac{0.244\ (6,20)}{0.228\ (5,80)}$

$\dfrac{0.157\ (4,00)}{0.150\ (3,80)}$ ⟨D⟩

1   8

Pin 1
Index Area

0.050 (1,27)

$\dfrac{0.020\ (0,51)}{0.012\ (0,31)}$

⊕ | 0.010 (0,25) Ⓜ

0.069 (1,75) Max

$\dfrac{0.010\ (0,25)}{0.004\ (0,10)}$

$\dfrac{0.010\ (0,25)}{0.005\ (0,13)}$

Gauge Plane

◁ | 0.004 (0,10)

Seating Plane

0.010 (0,25)   0°–8°

$\dfrac{0.050\ (1,27)}{0.016\ (0,40)}$

4040047−6/M   06/11

NOTES: A.   All linear dimensions are in inches (millimeters).
            B.   This drawing is subject to change without notice.
         ⟨C⟩   Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
         ⟨D⟩   Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
            E.   Reference JEDEC MS−012 variation AC.
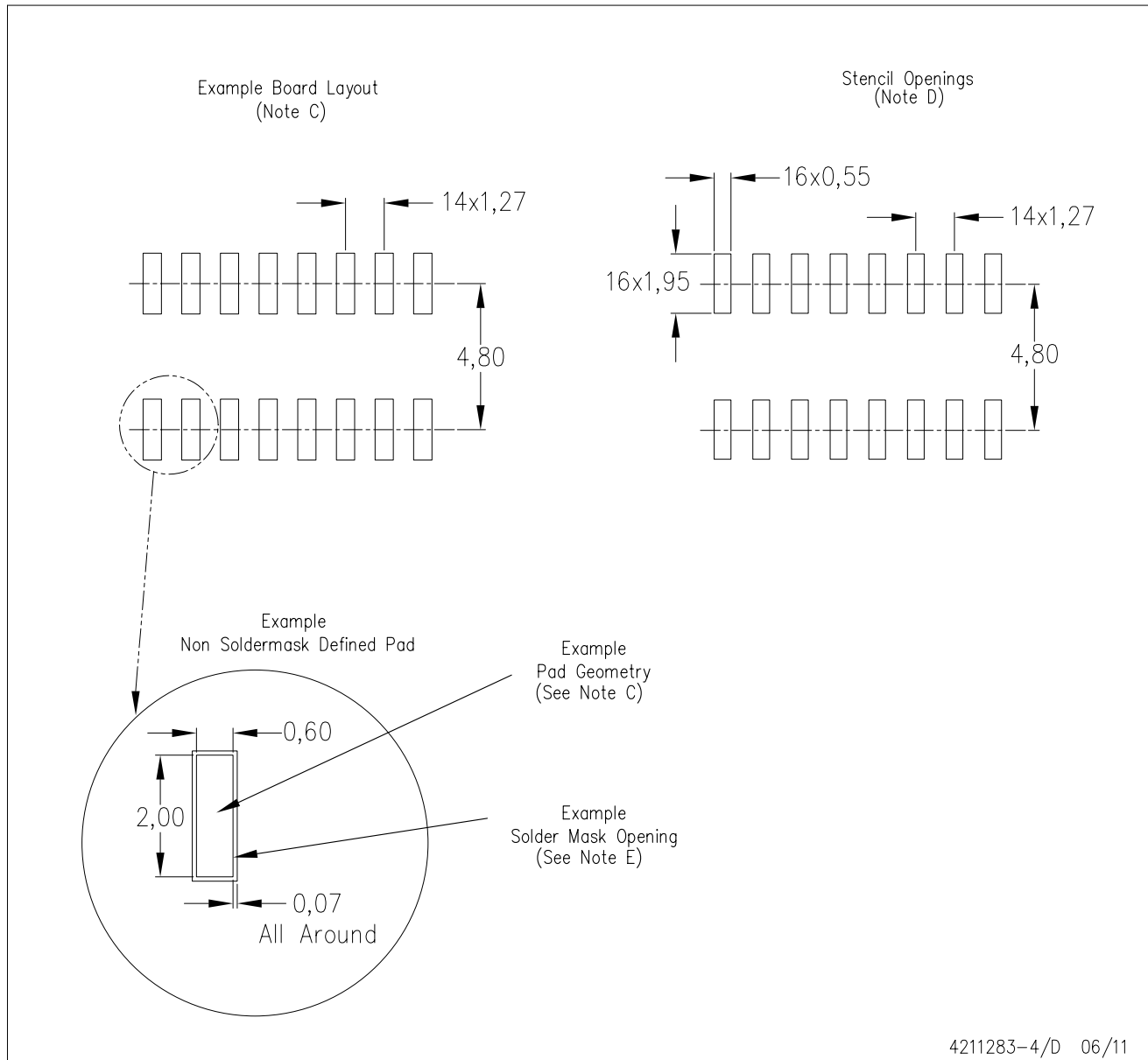
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INSTRUMENTS
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LAND PATTERN DATA

D (R−PDSO−G16)   PLASTIC SMALL OUTLINE

Example Board Layout
(Note C)

Stencil Openings
(Note D)

14x1,27

16x0,55

14x1,27

16x1,95

4,80

4,80

Example
Non Soldermask Defined Pad

Example
Pad Geometry
(See Note C)

0,60

2,00

Example
Solder Mask Opening
(See Note E)

0,07
All Around

4211283−4/D   06/11

NOTES: A. All linear dimensions are in millimeters.
         B. This drawing is subject to change without notice.
         C. Publication IPC−7351 is recommended for alternate designs.
         D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should
             contact their board assembly site for stencil design recommendations. Refer to IPC−7525 for other stencil recommendations.
         E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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PW (R−PDSO−G16)   PLASTIC SMALL OUTLINE

0,65

0,30
0,19

⊕ 0,10 Ⓜ

16   9

Ⓓ   4,50
    4,30

6,60
6,20

1   8

5,10
4,90

Ⓒ

0,15 NOM

Gage Plane

0,25

0°−8°

0,75
0,50

1,20 MAX

0,15
0,05

Seating Plane

⌒ 0,10

4040064−4/G 02/11

NOTES: A.   All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M−1994.
         B.   This drawing is subject to change without notice.
         Ⓒ   Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall
              not exceed 0,15 each side.
         Ⓓ   Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
         E.   Falls within JEDEC MO−153

PW (R−PDSO−G16)   PLASTIC SMALL OUTLINE
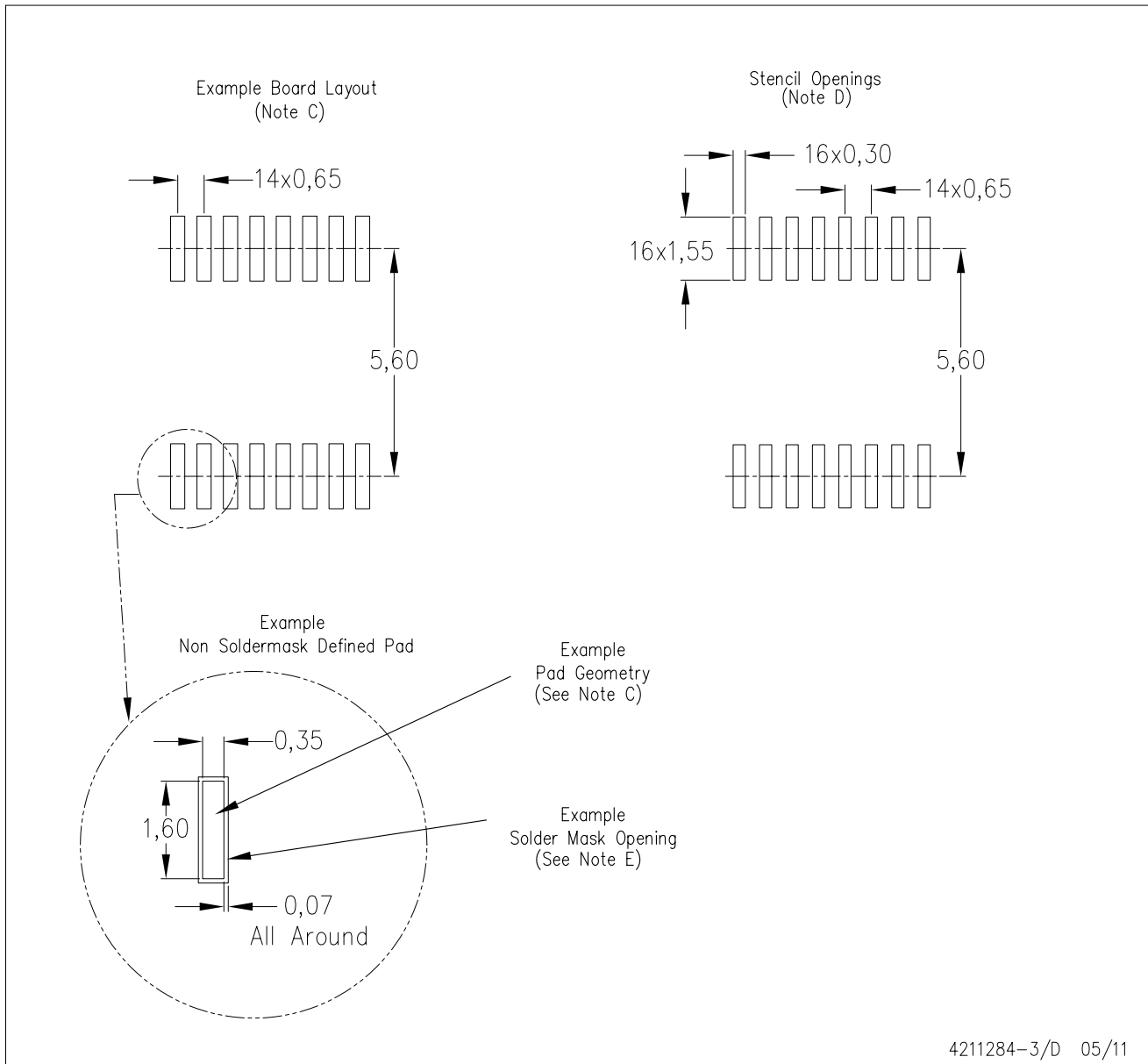
Example Board Layout
(Note C)

Stencil Openings
(Note D)

14x0,65

16x0,30

14x0,65

16x1,55

5,60

5,60

Example
Non Soldermask Defined Pad

Example
Pad Geometry
(See Note C)

0,35

1,60

Example
Solder Mask Opening
(See Note E)

0,07
All Around

4211284−3/D   05/11

NOTES: A.   All linear dimensions are in millimeters.
         B.   This drawing is subject to change without notice.
         C.   Publication IPC−7351 is recommended for alternate designs.
         D.   Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should
              contact their board assembly site for stencil design recommendations. Refer to IPC−7525 for other stencil recommendations.
         E.   Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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MECHANICAL DATA

NS (R-PDSO-G)**

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN

DIM	PINS **	14	16	20	24
A	MAX	10,50	10,50	12,90	15,30
A	MIN	9,90	9,90	12,30	14,70

4040062/C 03/03

NOTES: A. All linear dimensions are in millimeters.
        B. This drawing is subject to change without notice.
        C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

IMPORTANT NOTICE